

AMENDMENTS TO THE CLAIMS

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Claims 1-12 (Cancelled)

13. (Currently Amended) A method for manufacturing a package for accommodating electronic parts, comprising the steps of:

forming a buildup substrate having:

a core substrate;

a power source and/or a ground layer on a said core substrate,

a buildup interconnecting layer, and

signal lines on said buildup interconnecting layer;

adhering a stiffener to said signal lines ~~buildup substrate~~ with a conductive adhesive layer using a conductive adhesive; and

forming a grounding plane using said stiffener and said buildup substrate,

wherein said conductive adhesive layer is formed on said signal lines.

14. (Original) The method for manufacturing a package for accommodating electronic parts according to claim 13, further comprising the step of fixing said conductive adhesive layer at a grounding potential.

15. (Original) The method for manufacturing a package for accommodating electronic parts according to claim 14, further comprising the steps of:

providing a plurality of ground connecting pads on said buildup interconnecting layer;  
and

connecting said conductive adhesive layer having mainly a conductive adhesive to said plurality of ground connecting pads.

16. (Original) The method for manufacturing a package for accommodating electronic parts according to claim 13, further comprising the step of providing pads connected to said grounding plane on the surface of said buildup substrate as well as electrically connecting said pads to said conductive adhesive layer.

17. (Previously Amended) The method for manufacturing a package for accommodating electronic parts according to claim 16, further comprising the steps of:

providing a plurality of ground connecting pads on said buildup interconnecting layer;  
and

connecting said conductive adhesive layer having mainly a conductive adhesive to said plurality of ground connecting pads.

18. (Original) The method for manufacturing a package for accommodating electronic parts according to claim 13, further comprising the steps of:

providing a plurality of ground connecting pads on said buildup interconnecting layer;  
and

connecting said conductive adhesive layer having mainly a conductive adhesive to said plurality of ground connecting pads.